Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

MICROCHIP Semiconductor Device Type: EMA 008 SOIC 3.9mm NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				J-STD-609A Product Marking and/or Pkg. Labeling e4
		"Contained In"	% Total			49.26	(mg) Total	Mold Compound	% ot Total Weight	63.15
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm		,	·		
Silica, vitreous	60676-86-0	Mold Compound	53.678	41.868	536,775		Silica, vitreous	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	3.868	3.017	38,679		Epoxy Resin	Trade Secret	6.13	
Phenolic Resin	Trade Secret	Mold Compound	3.868	3.017	38,679		Phenolic Resin	Trade Secret	6.13	
Epoxy, Cresol Novolac	29690-82-2	Mold Compound	1.547	1.207	15,472		Epoxy, Cresol Novolac		2.45 0.30	
Carbon Black	1333-86-4	Mold Compound	0.189	0.148	1,895		Carbon Black	1333-86-4		
Copper	7440-50-8	Lead Frame	32.771	25.561	327,706			Total	100.00	
Iron	7439-89-6	Lead Frame	0.775	0.604	7,746	26.27	(mg) Total	Lead Frame	% of Total Weight	33.68
Phosphorous	7723-14-0	Lead Frame	0.084	0.066	842		Copper	7440-50-8	97.30	
Zinc (Metal)	7440-66-6	Lead Frame	0.051	0.039	505		Iron	7439-89-6	2.30	
Silver	7440-22-4	Die Attach	0.144	0.112	1,441		Phosphorous	7723-14-0	0.25	
Paraffins (petroleum), normal C5-20	64771-72-8	Die Attach	0.036	0.028	360		Zinc (Metal)	7440-66-6	0.15	
Epoxy resin	25036-25-3	Die Attach	0.010	0.008	99			Total	100.00	
Silicon	7440-21-3	Chip (Die)	1.270	0.991	12,700	0.15	(mg) Total	Die Attach	% of Total Weight	0.19
Gold	7440-57-5	Wire Bond	0.290	0.226	2,900		Silver	7440-22-4	75.83	
Nickel	7440-02-0	Plating on external leads (pins)	1.337	1.043	13,375	Par	affins (petroleum), normal C	64771-72-8	18.96	
	7440-05-3	Plating on external leads (pins)	0.050	0.039	496		Epoxy resin	25036-25-3	5.21	
Palladium									100.00	
Palladium Gold	7440-57-5	Plating on external leads (pins)	0.033	0.026	331			Total	100.00	
		Plating on external leads (pins) TOTALS		0.026 78.000	331 1,000,001	0.99	Total (mg)	Total Chip (Die)	% of Total Weight	1.27
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